

## 1. General description

Planar passivated four quadrant triac in a SOT186A (TO-220F) plastic package intended for use in general purpose bidirectional switching and phase control applications.

## 2. Features and benefits

- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Less sensitive gate for improved noise immunity
- Triggering in all four quadrants
- Isolated package

## 3. Applications

- General purpose motor control
- General purpose switching

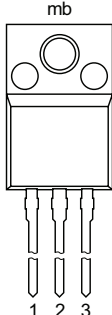
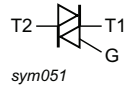
## 4. Quick reference data

Table 1. Quick reference data

| Symbol                         | Parameter                            | Conditions  | Values |     |     | Unit |
|--------------------------------|--------------------------------------|---|--------|-----|-----|------|
| <b>Absolute maximum rating</b> |                                      |   |        |     |     |      |
| $V_{DRM}$                      | repetitive peak off-state voltage    |   | 600    |     |     | V    |
| $I_{T(RMS)}$                   | RMS on-state current                 | full sine wave; $T_h \leq 88\text{ °C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>           | 6      |     |     | A    |
| $I_{TSM}$                      | non-repetitive peak on-state current | full sine wave; $T_{j(\text{init})} = 25\text{ °C}$ ;<br>$t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | 65     |     |     | A    |
| Symbol                         | Parameter                            | Conditions  | Min    | Typ | Max | Unit |
| <b>Static characteristics</b>  |                                      |   |        |     |     |      |
| $I_{GT}$                       | gate trigger current                 | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                           | -      | 5   | 35  | mA   |
|                                |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                           | -      | 8   | 35  | mA   |
|                                |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                           | -      | 11  | 35  | mA   |
|                                |                                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                           | -      | 30  | 70  | mA   |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description             | Simplified outline  | Graphic symbol  |
|-----|--------|-------------------------|---|---|
| 1   | T1     | main terminal 1         |  |  |
| 2   | T2     | main terminal 2         |   |   |
| 3   | G      | gate                    |   |   |
| mb  | n.c.   | mounting base; isolated |   |   |

## 6. Ordering information

Table 3. Ordering information

| Type number | Package |   |         |
|-------------|---------|---|---------|
|             | Name    | Description   | Version |
| BT236X-600  | TO-220F | plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack" | SOT186A |

## 7. Marking

Table 4. Marking codes

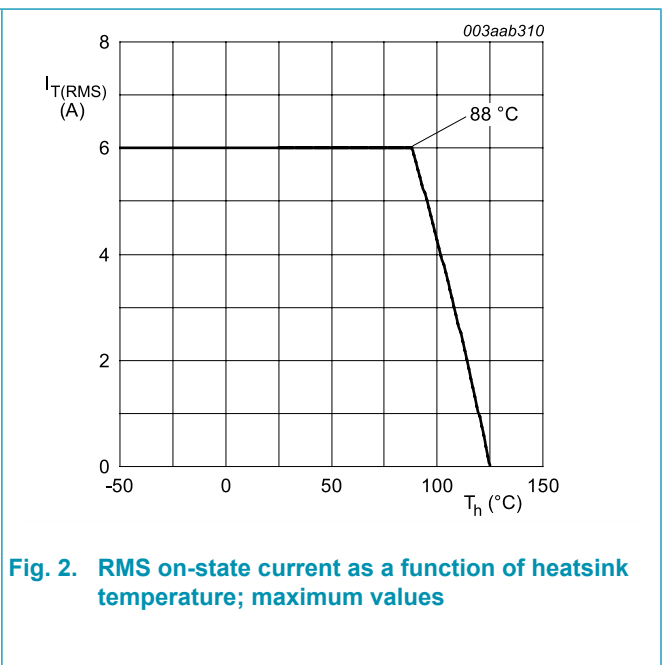
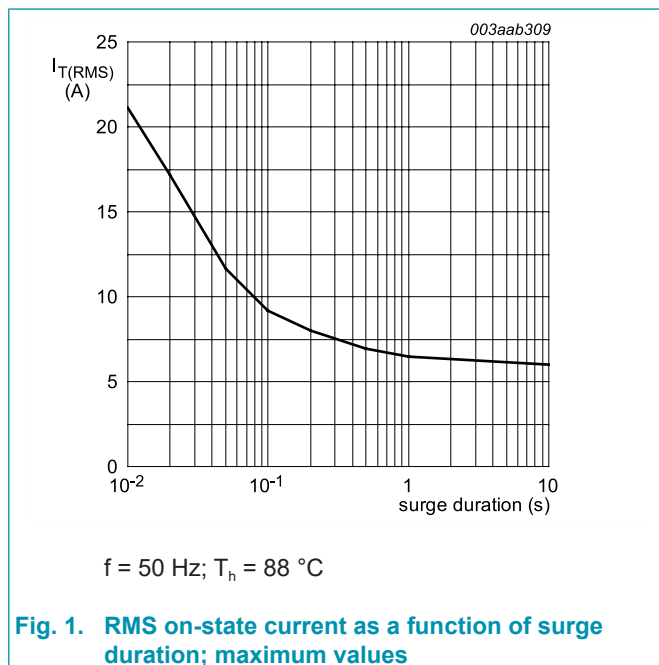
| Type number | Marking codes |
|-------------|---------------|
| BT236X-600  | BT236X-600    |

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions  | Values     | Unit                   |
|--------------|--------------------------------------|---|------------|------------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |   | 600        | V                      |
| $I_{T(RMS)}$ | RMS on-state current                 | full sine wave; $T_h \leq 88\text{ }^\circ\text{C}$ ;<br><a href="#">Fig 1</a> ; <a href="#">Fig 2</a> ; <a href="#">Fig 3</a>            | 6          | A                      |
| $I_{TSM}$    | non-repetitive peak on-state current | full sine wave; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ;<br><a href="#">Fig 4</a> ; <a href="#">Fig 5</a> | 65         | A                      |
|              |                                      | full sine wave; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$  | 71         | A                      |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ ms}$ ; SIN  | 21         | $\text{A}^2\text{s}$   |
| $dl_T/dt$    | rate of rise of on-state current     | $I_G = 70\text{ mA}$ ; T2+ G+   | 50         | $\text{A}/\mu\text{s}$ |
|              |                                      | $I_G = 70\text{ mA}$ ; T2+ G-   | 50         | $\text{A}/\mu\text{s}$ |
|              |                                      | $I_G = 70\text{ mA}$ ; T2- G-   | 50         | $\text{A}/\mu\text{s}$ |
|              |                                      | $I_G = 140\text{ mA}$ ; T2- G+  | 10         | $\text{A}/\mu\text{s}$ |
| $I_{GM}$     | peak gate current                    |   | 2          | A                      |
| $P_{GM}$     | peak gate power                      |   | 5          | W                      |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period   | 0.5        | W                      |
| $T_{stg}$    | storage temperature                  |   | -40 to 150 | $^\circ\text{C}$       |
| $T_j$        | junction temperature                 |   | 125        | $^\circ\text{C}$       |



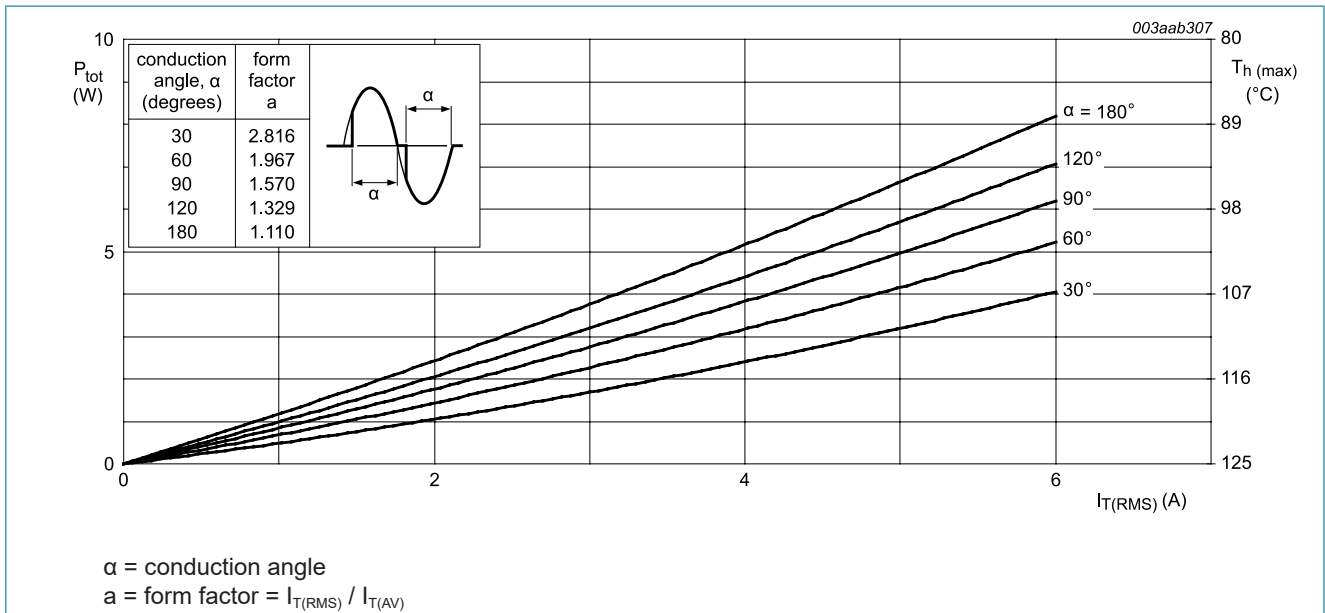


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

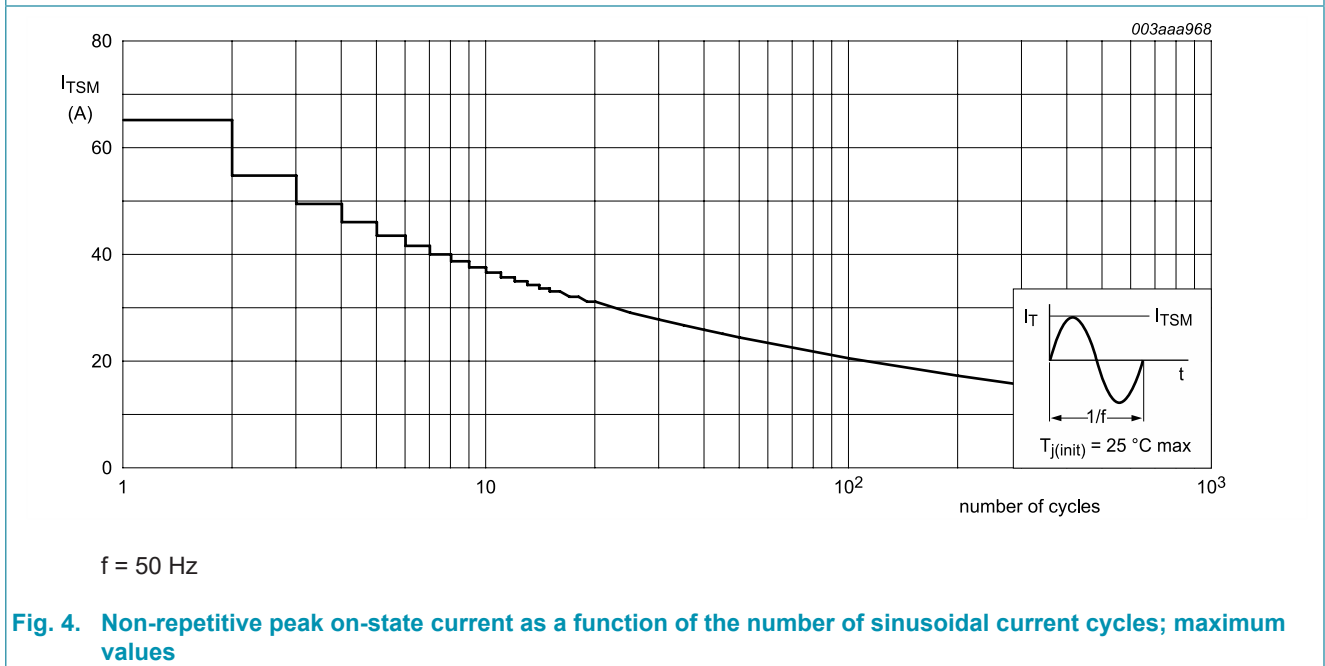


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

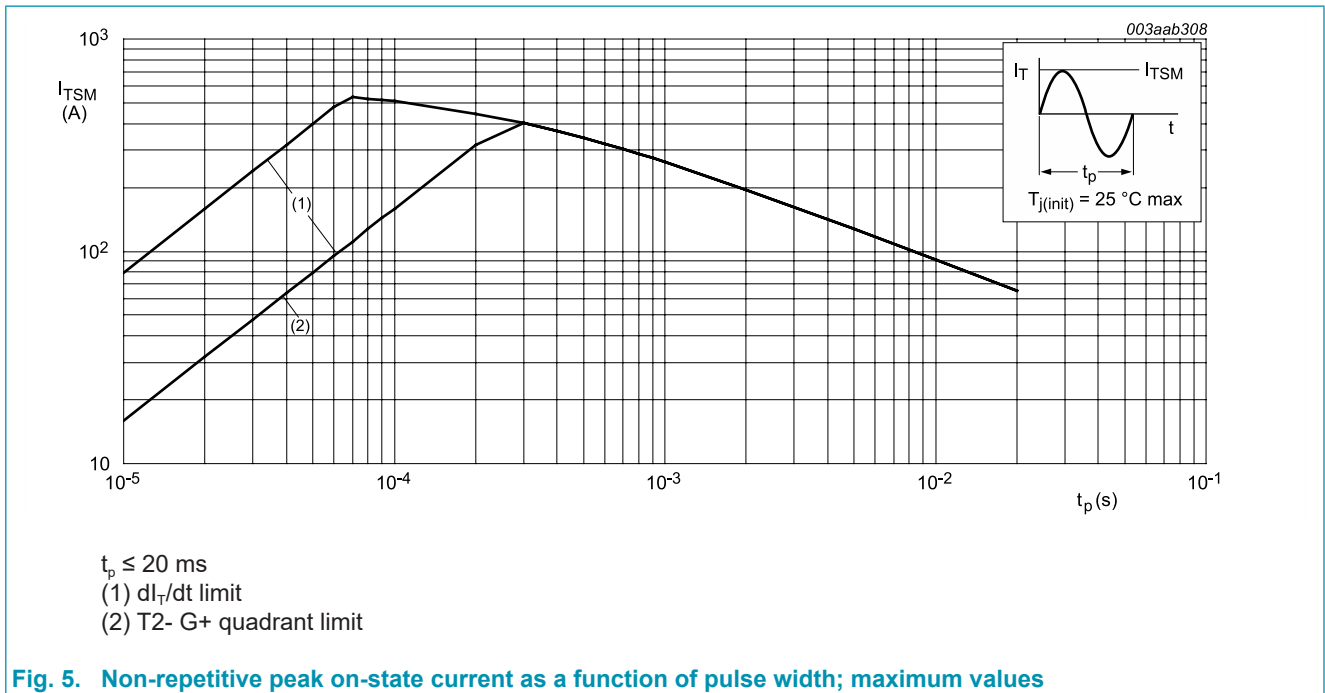


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol        | Parameter                                    | Conditions   | Min | Typ | Max | Unit |
|---------------|--|--|-----|-----|-----|------|
| $R_{th(j-h)}$ | thermal resistance from junction to heatsink | full or half cycle; with heatsink compound; Fig 6    | -   | -   | 4.5 | K/W  |
|               |  | full or half cycle; without heatsink compound; Fig 6 | -   | -   | 6.5 | K/W  |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient  | in free air  | -   | 55  | -   | K/W  |

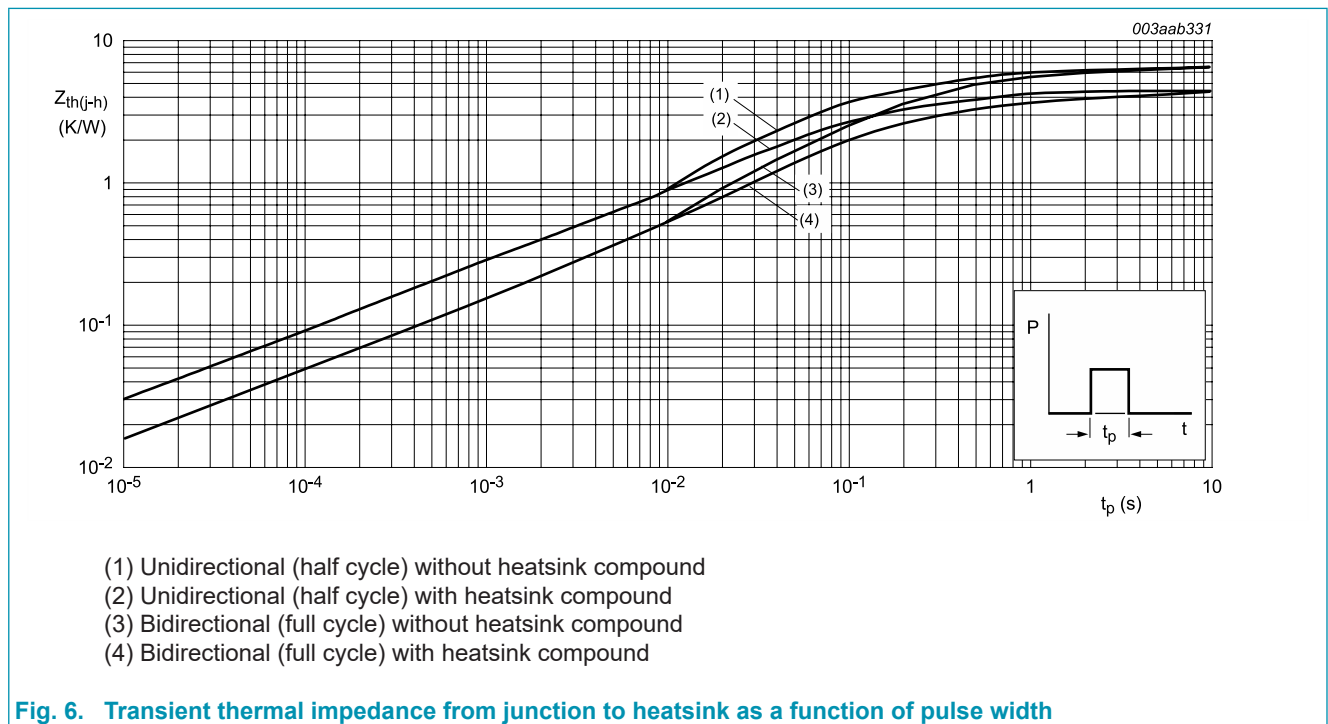


Fig. 6. Transient thermal impedance from junction to heatsink as a function of pulse width

## 10. Isolation characteristics

Table 7. Isolation characteristics

| Symbol          | Parameter             | Conditions  | Min | Typ | Max  | Unit |
|-----------------|-----------------------|---|-----|-----|------|------|
| $V_{isol(RMS)}$ | RMS isolation voltage | from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; T <sub>h</sub> = 25 °C | -   | -   | 2500 | V    |
| $C_{isol}$      | isolation capacitance | from main terminal 2 to external heatsink; f = 1 MHz; T <sub>h</sub> = 25 °C  | -   | 10  | -    | pF   |

## 11. Characteristics

Table 8. Characteristics

| Symbol                         | Parameter                             | Conditions  | Min  | Typ | Max  | Unit       |
|--------------------------------|---------------------------------------|---|------|-----|------|------------|
| <b>Static characteristics</b>  |                                       |   |      |     |      |            |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 7</a>                         | -    | 5   | 35   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 7</a>                         | -    | 8   | 35   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 7</a>                         | -    | 11  | 35   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G+;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 7</a>                         | -    | 30  | 70   | mA         |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G+;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 8</a>                         | -    | 7   | 30   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G-;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 8</a>                         | -    | 16  | 45   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G-;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 8</a>                         | -    | 5   | 30   | mA         |
|                                |                                       | $V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G+;$<br>$T_J = 25\text{ °C};$ <a href="#">Fig. 8</a>                         | -    | 7   | 45   | mA         |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}; T_J = 25\text{ °C};$ <a href="#">Fig. 9</a>   | -    | 5   | 20   | mA         |
| $V_T$                          | on-state voltage                      | $I_T = 10\text{ A}; T_J = 25\text{ °C};$ <a href="#">Fig. 10</a>  | -    | 1.3 | 1.65 | V          |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_J = 25\text{ °C};$<br><a href="#">Fig. 11</a>                                   | -    | 0.7 | 1    | V          |
|                                |                                       | $V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_J = 125\text{ °C};$<br><a href="#">Fig. 11</a>                                 | 0.25 | 0.4 | -    | V          |
| $I_D$                          | off-state current                     | $V_D = 600\text{ V}; T_J = 125\text{ °C}$   | -    | 0.1 | 0.5  | mA         |
| <b>Dynamic characteristics</b> |                                       |   |      |     |      |            |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 402\text{ V}; T_J = 125\text{ °C}; (V_{DM} = 67\%$<br>of $V_{DRM});$ exponential waveform; gate<br>open circuit | 100  | 250 | -    | V/ $\mu$ s |
| $dV_{com}/dt$                  | rate of change of commutating voltage | $V_D = 400\text{ V}; T_J = 95\text{ °C}; I_T = 6\text{ A};$<br>$di_{com}/dt = 3.6\text{ A/ms};$ gate open circuit         | -    | 20  | -    | V/ $\mu$ s |
| $t_{gt}$                       | gate-controlled turn-on time          | $V_D = 600\text{ V}; I_{TM} = 12\text{ A}; I_G = 0.1\text{ A};$<br>$di_G/dt = 5\text{ A}/\mu\text{s}$                     | -    | 2   | -    | $\mu$ s    |

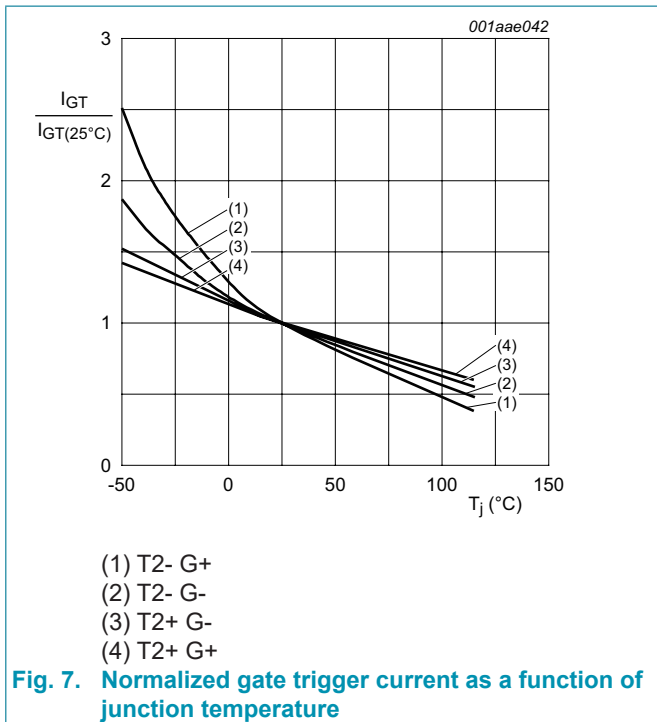


Fig. 7. Normalized gate trigger current as a function of junction temperature

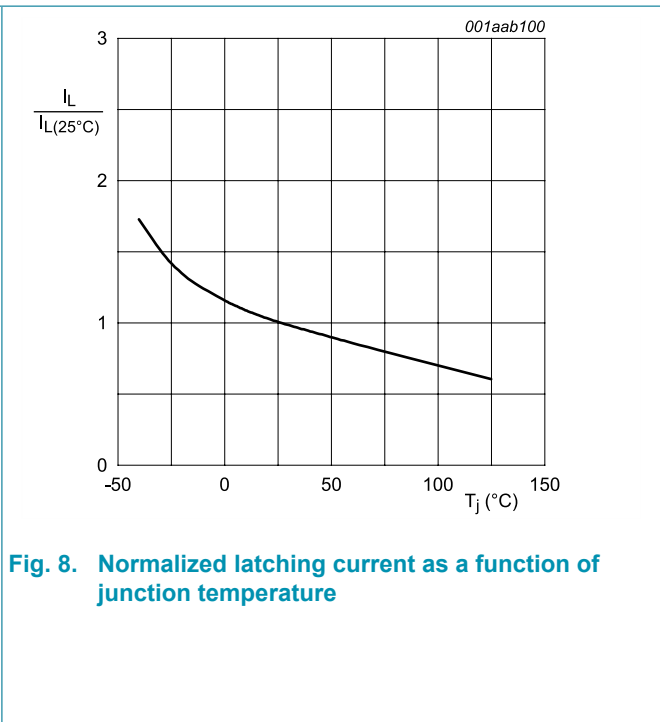


Fig. 8. Normalized latching current as a function of junction temperature

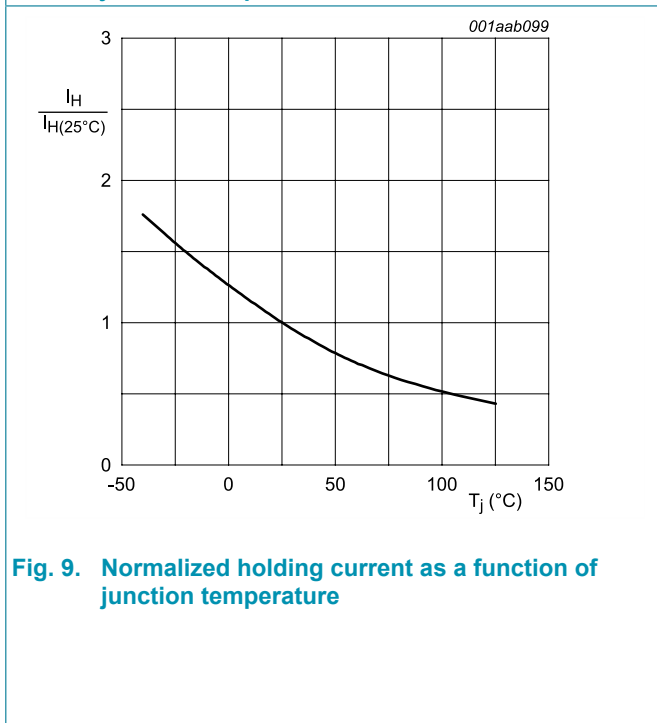


Fig. 9. Normalized holding current as a function of junction temperature

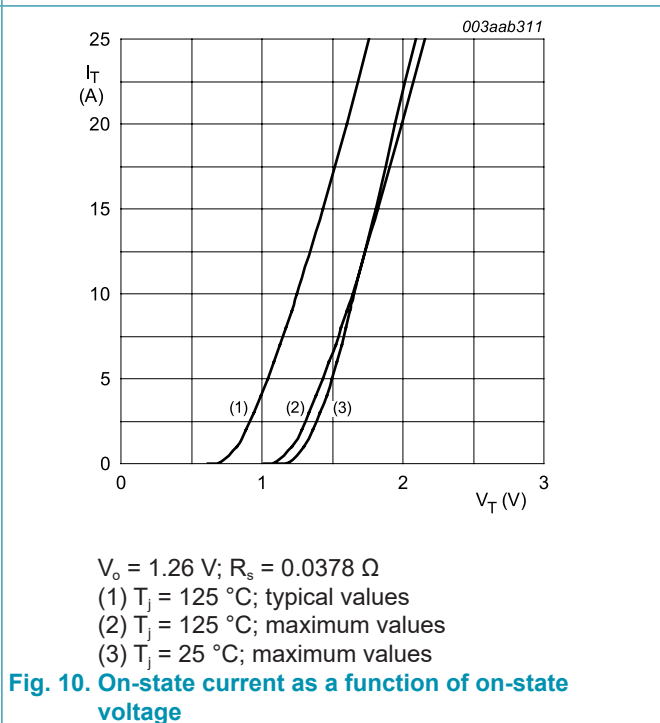


Fig. 10. On-state current as a function of on-state voltage



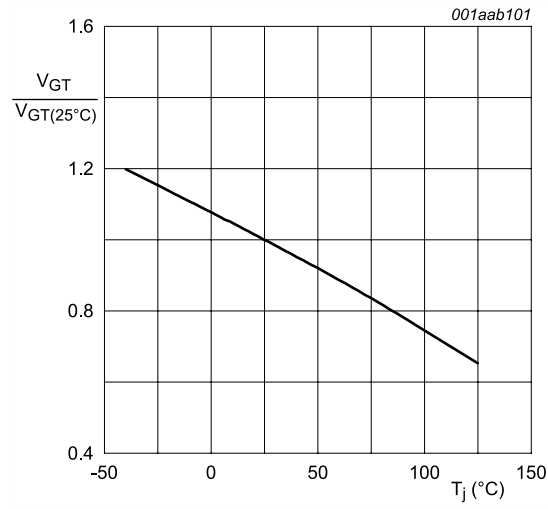
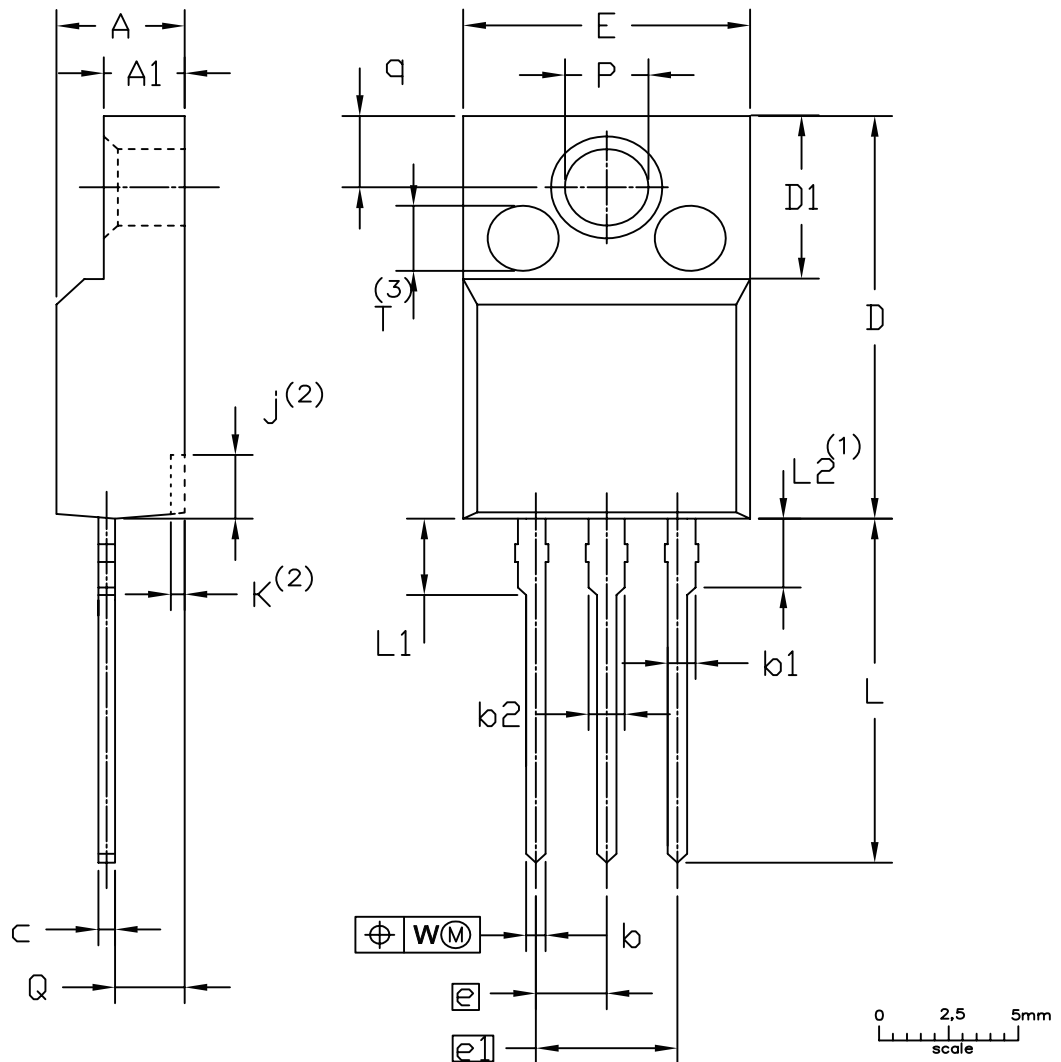


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

## 12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"

SOT186A



| UNIT | A   | A <sub>1</sub> | b   | b <sub>1</sub> | b <sub>2</sub> | c   | D    | D <sub>1</sub> | E    | e    | e <sub>1</sub> | j <sup>(2)</sup> | k <sup>(2)</sup> | L    | L <sub>1</sub> | L <sub>2</sub> <sup>(1)</sup><br>max. | P   | Q   | q   | W   | T <sup>(3)</sup> |
|------|-----|----------------|-----|----------------|----------------|-----|------|----------------|------|------|----------------|------------------|------------------|------|----------------|---------------------------------------|-----|-----|-----|-----|------------------|
| mm   | 4.6 | 2.9            | 0.9 | 1.1            | 1.4            | 0.7 | 15.8 | 6.5            | 10.3 |      |                | 2.7              | 0.6              | 14.4 | 3.30           |                                       | 3.2 | 2.6 | 3.0 | 0.4 | 2.5              |
|      | 4.0 | 2.5            | 0.7 | 0.9            | 1.0            | 0.4 | 15.2 | 6.3            | 9.7  | 2.54 | 5.08           | 1.7              | 0.4              | 13.5 | 2.79           | 3                                     | 3.0 | 2.3 | 2.6 |     |                  |

- Notes
- Terminal dimensions within this zone are uncontrolled
  - Dot lines area designs may vary
  - Eject pin mark is for reference only

| OUTLINE VERSION | REFERENCES |                |       | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------------|-------|---------------------|------------|
|                 | IEC        | JEDEC          | JEITA |                     |            |
| SOT186A         |            | 3 LEADS TO220F |       |                     | 2013-11-14 |

## 13. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 24 April 2018

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- Защита от снятия компонента с производства.



#### Как с нами связаться

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